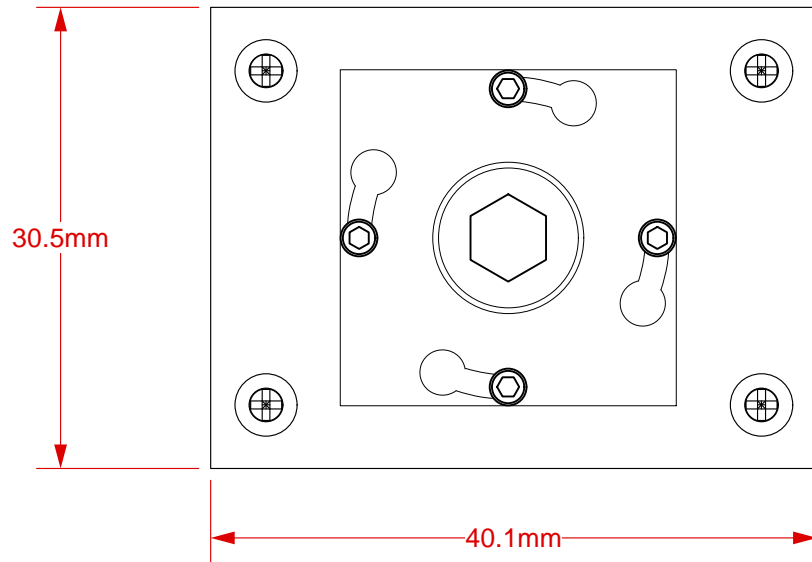


Top View

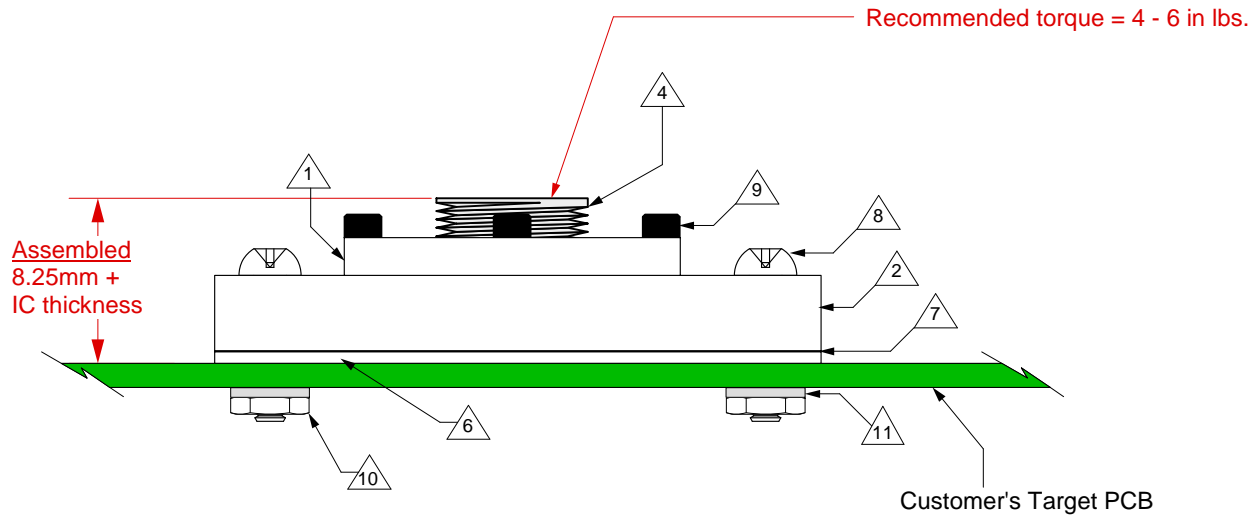


GHz BGA Socket - Direct mount, solderless


Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View

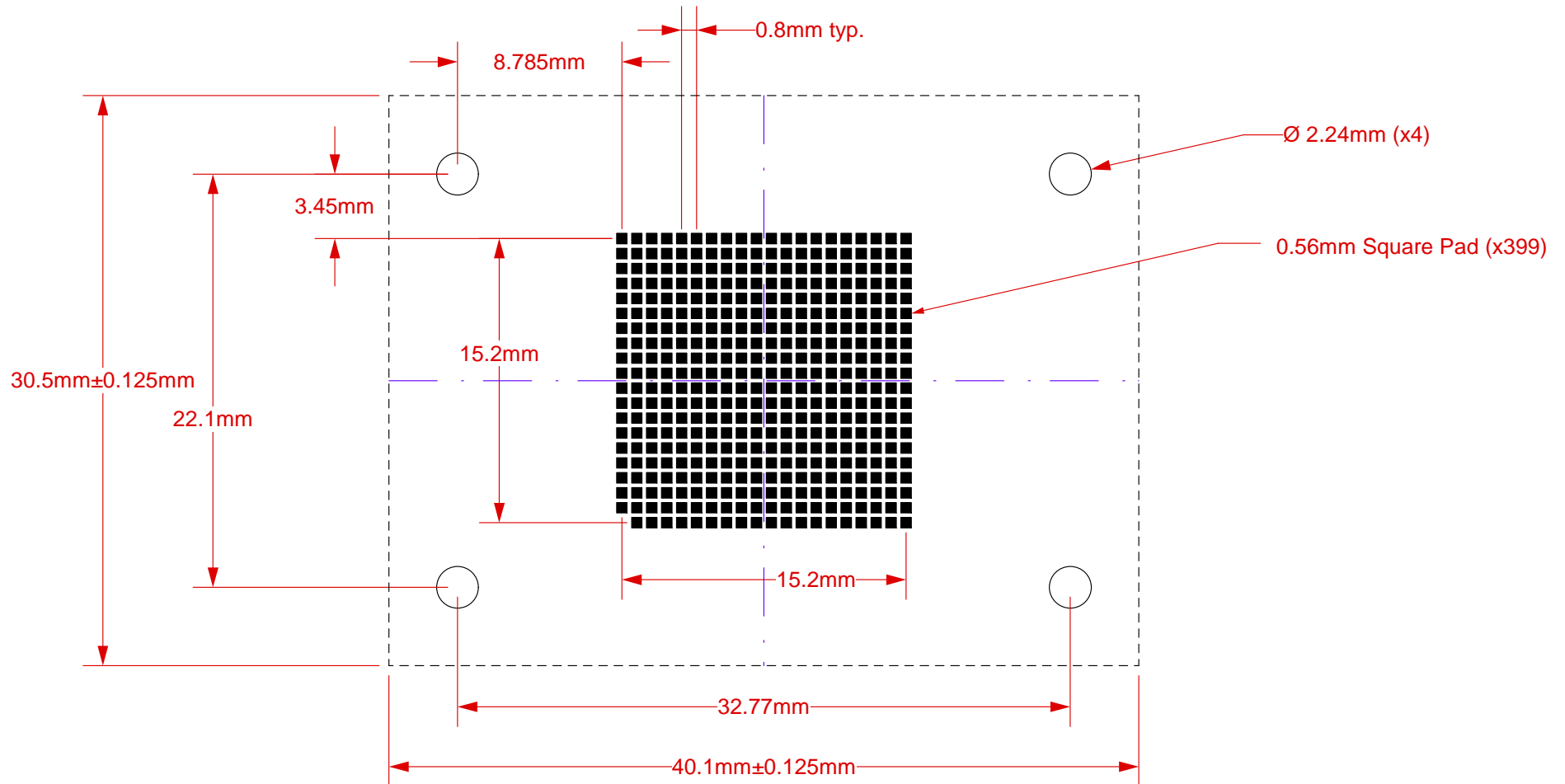


- 1 Socket Lid: Black anodized 6061 Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized 6061 Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized 6061 Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Black anodized 6061 Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.75mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Philips round head, alloy steel with black oxide finish, 2-56 fine thread , 12.7mm long.
- 9 Socket lid screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 4.76mm long.
- 10 Socket base nut: 18-8 Stainless steel, 2-56 fine thread, 4.76mm width, 1.59mm height.
- 11 Nylon washer: 2.4mm ID; 4.76mm OD 0.5mm thickness.

	SG-BGA-6057 Drawing	Status: Released	Scale: 2:1	Rev: B
	© 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 8/13/02	
		File: SG-BGA-6057 Dwg.mcd	Modified: 10/15/02	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




Target PCB Recommendations

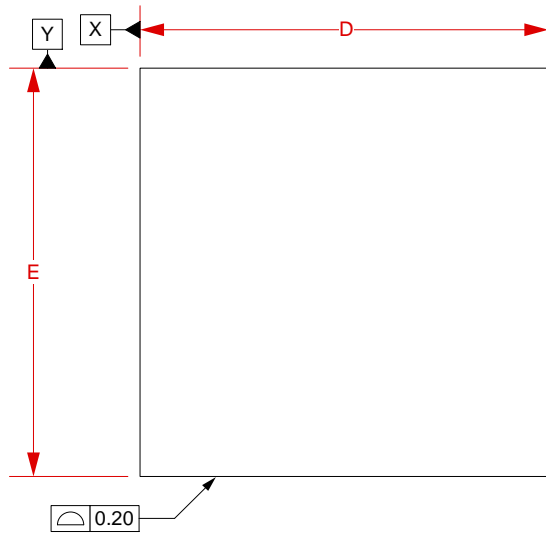
- Total thickness: 1.6mm min.
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

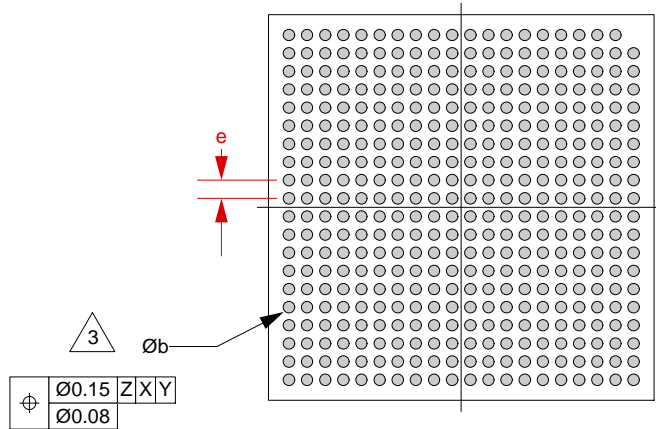
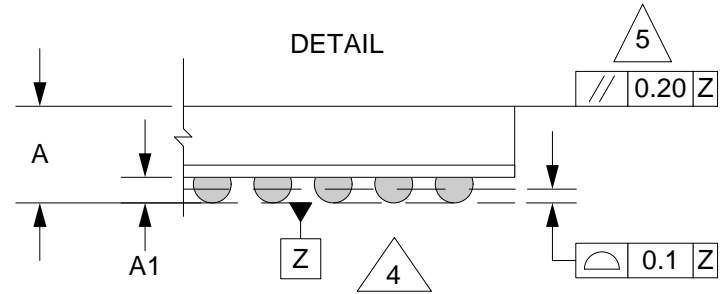
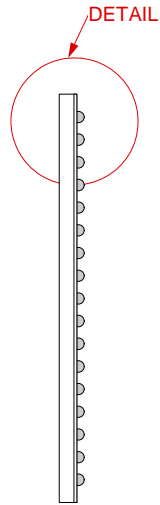
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

	SG-BGA-6057 Drawing	Status: Released	Scale: 3:1	Rev: B
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TOP VIEW



SIDE VIEW




BOTTOM VIEW

DIM	MIN	MAX
A		1.7
A1	0.25	0.35
b		0.45
D	17.00 BSC	
E	17.00 BSC	
e	0.8 BSC	

Array (20x20)-1= 399 Balls

1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

	SG-BGA-6057 Drawing	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-6057 Dwg.mcd	Modified: 10/15/02	